

## Production Capability

Layers Counts	1-20 layers
Base Material	Fr-4
	CEM-1
	Teflon
Copper Foil	18 - 35 - 70 - 105 $\mu$ m
Max board size	450 x 750 mm
Min. Board thickness	1-2 layer 0,2 mm
	4 layer 0,4 mm
	6 layer 0,6 mm
	10 layer 1,0 mm
Surface Finishing	HASL (Tin Lead and Pb Free)
	Immersion Gold
	OSP
	Immersion Tin
	Immersion Silver
Profile	Rount, Punch, V-cut, Chanfer
Min. Hole size	0,2 mm
Min. Line Width and Spacing	0,10 mm/0,10 mm
Min. S/M Pitch	0,25 mm
BGA	0,5 mm
Hole position deviation	+/- 0,05 mm
Impedance	+/- 10 %
Solder Mask	Black, Green, Red, Blue, White
Solder Mask Thickness	10 $\mu$ m
Gerber Electronic Files	RS-274-D, AutoCAD DXF



## Ci.Pi.board<sup>s.r.l.</sup>

PRODUZIONE CIRCUITI STAMPATI

Via Belizzi, 47

29100 Piacenza (PC) ITALY

tel. +39 0523.609530

fax. +39 0523.644875

[www.cipiboard.it/new](http://www.cipiboard.it/new)

e-mail: [info@cipiboard.it](mailto:info@cipiboard.it)

